

SPACE EQUIPMENT WITH COTS PARTS - FROM DESIGN TO PRODUCT

Dr. Jens Haala, TESAT Spacecom

Agenda





- » Equipment design with Classic Space
- » Equipment design with COTS
 - » Challenges
 - » Risk
- » Mitigation of Risks

EQUIPMENT DEVELOPMENT FOR CLASSIC SPACE Design Strategy



The Classic Way



EQUIPMENT DEVELOPMENT FOR CLASSIC SPACE Design Strategy



The Old Way



USAGE OF COTS PARTS Basic Considerations





- Lower Quality Level (less Screening/LAT)
- » Automotive
- » Industrial

- Consequences:
- » High Volume
- » Big Lot Size
- » Small Variety





- Typically Additional Tests needed
- » Lot Acceptance
- » Radiation
- » Single Event Effect
- » Screening

- Risks: » Traceability » Tests may fail → Part not flight-worthy
 - » Waste of Money



EQUIPMENT DEVELOPMENT WITH COTS Design Strategy





- » Equipment function is given
- » Identify building blocks
- » Identify parts to create building block by function
- - » Collect part candidates information
 - » Pre-selection

EQUIPMENT DEVELOPMENT WITH COTS Design Strategy





- 7 -

EQUIPMENT DEVELOPMENT WITH COTS Design Strategy







- » Thermal cycling
- » Radiation analysis
- » Design Review

No Surprise!



- » Equipment function is given
- » Identify building blocks
- » Identify parts to create building block by function
- » Collect part candidates information
- » Pre-selection
- » Design release
- » Adapt pre-selection
- » Identify missing screening/LAT tests
- » perform delta tests
- » perform radiation test
- » check status
- » propose alternatives
- » Design release...







RISK MITIGATION Expensive Test Cost





$\langle \rangle$	
D	

- » Check availability of parts
- » Check the technology (CMOS, BiCMOS, bipolar)
- » Define critical effects for the given device type (N-MOSFETs, OpAmps, voltage ref., ...)
- » Check bias condition within application wrt. radiation sensitivity
- » Reduce the number of different parts (e.g. MOSFETs)
- » Define radiation source wrt. parts related critical parameters Examples:
 - » MOSFET: Heavy ion
 - » FPGA: Mitigation techniques and/or laser SEE testing
 - » OpAmps: TID & SEE

GENERAL: SEE TESTING

- » Open devices with JetEtcher, Laser, chemical ablation, ...
- » 1st step: Checking for destructive SEE by testing with Xe-ions (LET = 62.5 MeV/mg/cm^2)
- (\circ) » Application conditions; not at (de-)rated bias voltage conditions
 - » Regular coordination with development engineers
- » Avoid to prepare detailed test plans
- » Avoid extensive test board design
- » Do not prepare test reports for failed parts

Target: Optimized thru-put time, fast results

- » Test at UCL-HIF in Belgium
 - » No transport issues
 - » Pre booking initialized
 - » Easy access to the device under test













GENERAL: TID TESTING

TESAT RESERVES ALL RIGHTS INCL. INDUSTRIAL PROPERTY RIGHTS AND ALL RIGHTS OF DISPOSAL.

- » Fully automated measurement equipment developed to test different part types in parallel
- » Generic mother-board and part-specific daughter-board
- » Regular coordination with development engineers
 - » Checking for relevant parameters
 - » Apply application conditions
- » Avoid to prepare detailed test plans and test reports
- » Adapt daughter board for subsequent test campaigns

Target: Optimized thru-put time, fast results

- » Test at F-INT in Euskirchen
 - » No transport issues
 - » Pre booking initialized
 - » Test data will be provided w/o delay









CONCLUSION





» Use of COTS parts require early interaction:
 EEE Parts Engineer ⇔ Equipment Developer



- » EEE Parts cost are low
 But: Test costs may eat up savings
 - → Change Equipment Development Process to mitigate risks and save costs



- » Selection of parts & tests require experience
 - » Save Test costs
 - » Save development time (no redesign)





SEVILLE - SPAIN 6-8 NOVEMBER

THANKS FOR YOUR ATTENTION

Dr. Jens Haala

Tesat-Spacecom GmbH & Co. KG Gerberstraße 49 71522 Backnang www.tesat.de